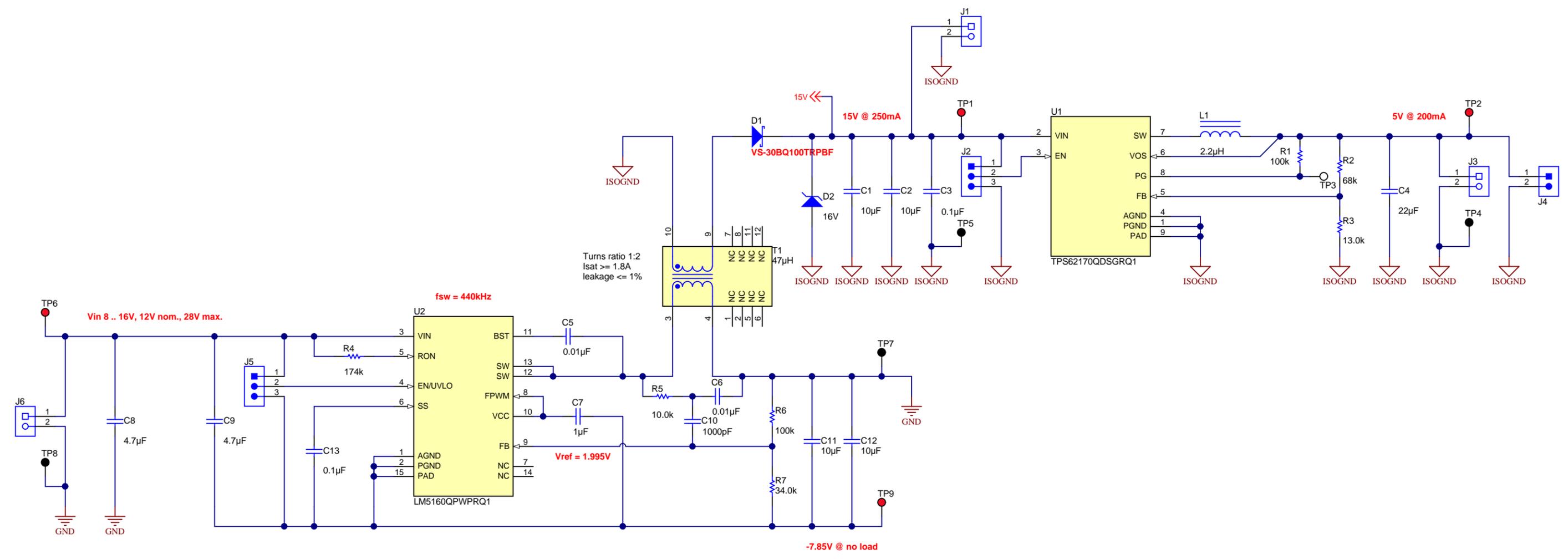


Revision History	
Revision	Notes
A	* preliminary
B	* built & tested

Design Notes:
 - D2 only necessary for no load conditions



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Number: PMP30227	Rev: B	Designed for: Public Release	Mod. Date: 7/18/2017
SVN Rev: Version control disabled	Assembly Variant: 001	Project Title: Automotive Flyback-Boost Bias Supply	Sheet: 1 of 1
Drawn By:	File: PMP30227RevB.SchDoc	Sheet Title: PMP30227RevB	Size: B
Engineer: M Zehndner	Contact: http://www.ti.com/support		

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